

DESCRIPTION

The MXN8260 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. It can be used in a wide variety of applications.

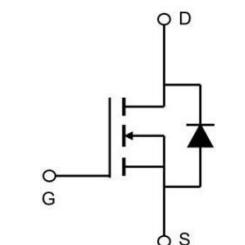
GENERAL FEATURES

- $V_{DS}=20V$, $I_D=22A$
 $R_{DS(ON)}(\text{Typ.})=4.2\text{m}\Omega$ @ $V_{GS}=2.5V$
 $R_{DS(ON)}(\text{Typ.})=3.2\text{m}\Omega$ @ $V_{GS}=4.5V$
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

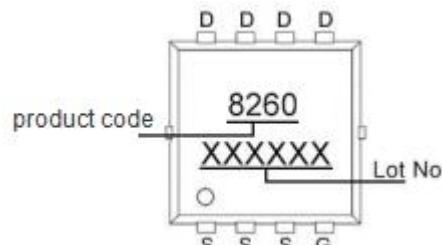
APPLICATION

- PWM applications
- Load switch

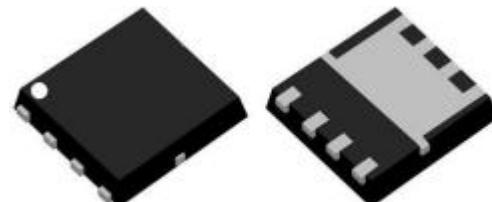
PINOUT



Schematic diagram



Marking and pin Assignment



PDFN3.3x3.3-8L top & bottom view

ORDERING INFORMATION

Part Number	Storage Temperature	Package	Devices Per Reel
MXN8260	-55°C to 150°C	PDFN3.3x3.3-8L	3000

ABSOLUTE MAXIMUM RATINGS($T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Drain Current-Continuous	I_D	22	A
Drain Current-Continuous($T_c=100^\circ\text{C}$)	I_D	17	A
Pulsed Drain Current ^(Note1)	I_{DM}	88	A
Maximum Power Dissipation	P_D	28	W
Avalanche Current	I_{AS}	66	A
Avalanche Energy($L=0.1\text{mH}$)	E_{AS}	218	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE

Thermal Resistance, Junction-to-Case ^(Note2)	$R_{\theta JC}$	4.5	°C/W
---	-----------------	-----	------

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Note 2. Surface Mounted on FR4 Board, $t \leq 10$ sec.


ELECTRICAL CHARACTERISTICS($T_C=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
-----------	--------	------------	-----	-----	-----	------

Off Characteristics

Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	20	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA

On Characteristics^(Note2)

Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.45	0.7	1.1	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=15\text{A}$	-	4.2	5.4	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=20\text{A}$	-	3.2	4	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=10\text{A}$	-	40	-	S

Dynamic Characteristics^(Note3)

Input Capacitance	C_{iss}	$V_{\text{DS}}=10\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2700	-	pF
Output Capacitance	C_{oss}		-	520	-	pF
Reverse Transfer Capacitance	C_{rss}		-	440	-	pF

Switching Characteristics

Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=10\text{V}, R_{\text{L}}=0.5\Omega, V_{\text{GS}}=5\text{V}, R_{\text{G}}=3\Omega$	-	7.5	-	nS
Turn-on Rise Time	t_{r}		-	15	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	72	-	nS
Turn-Off Fall Time	t_{f}		-	21	-	nS
Total Gate Charge	Q_{g}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=20\text{A}, V_{\text{GS}}=4.5\text{V}$	-	32	-	nC
Gate-Source Charge	Q_{gs}		-	5.2	-	nC
Gate-Drain Charge	Q_{gd}		-	8	-	nC

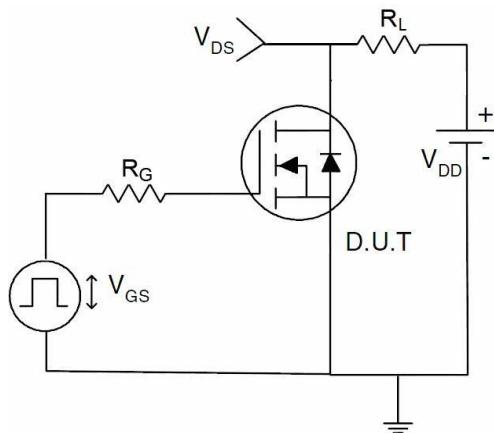
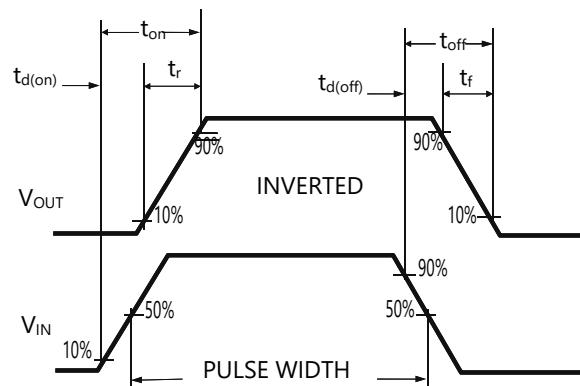
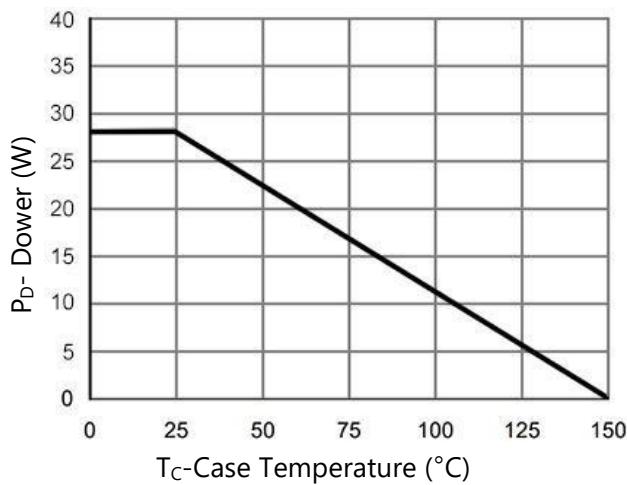
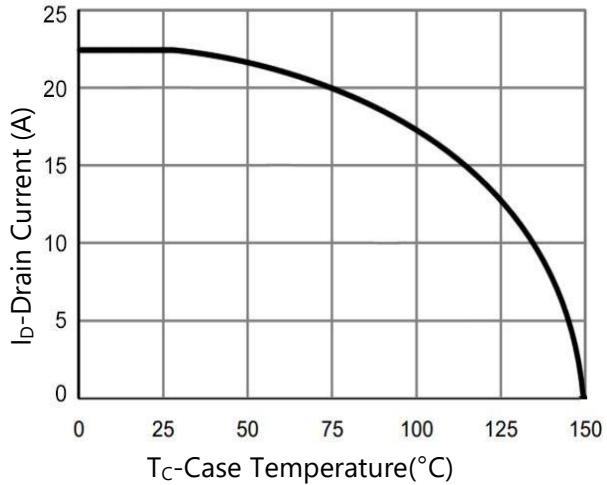
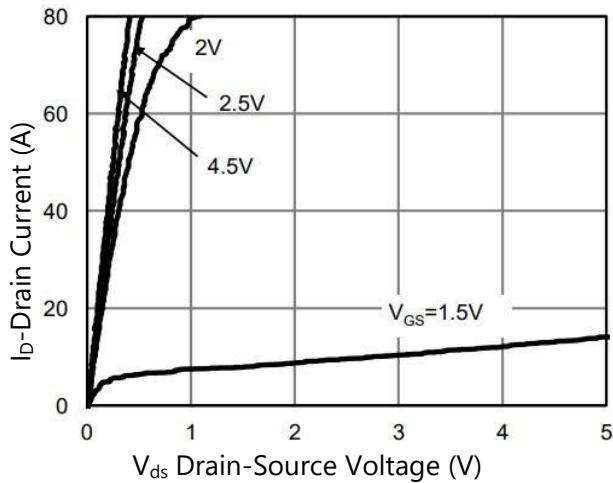
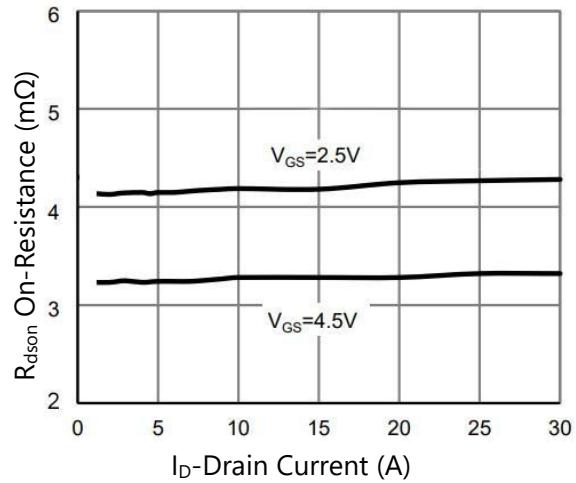
Drain-Source Diode Characteristics

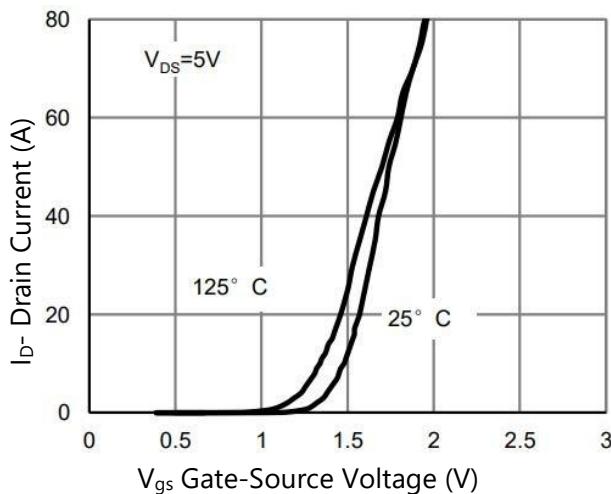
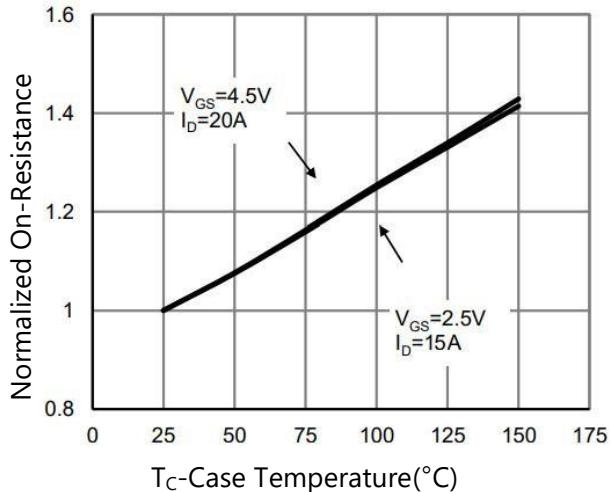
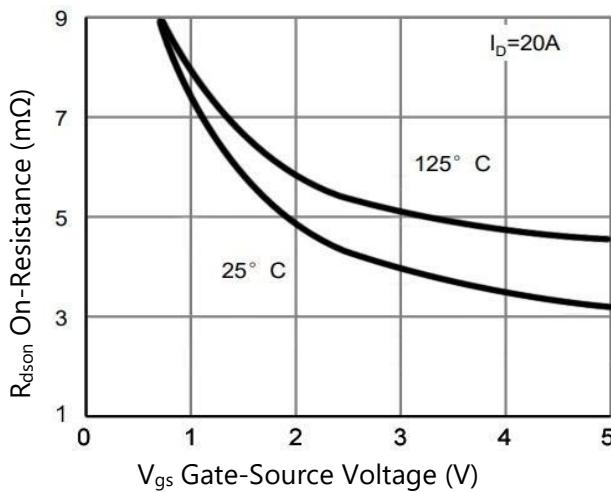
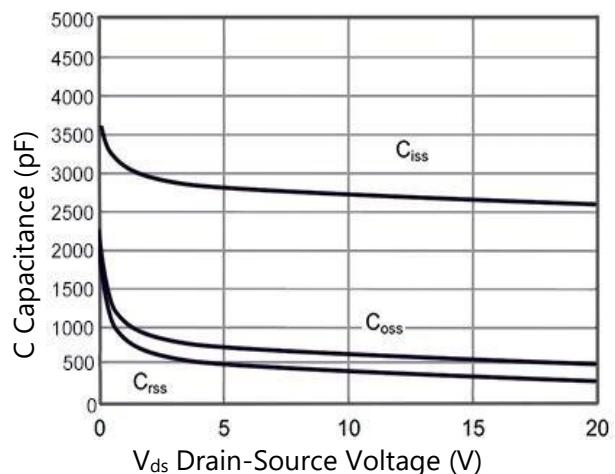
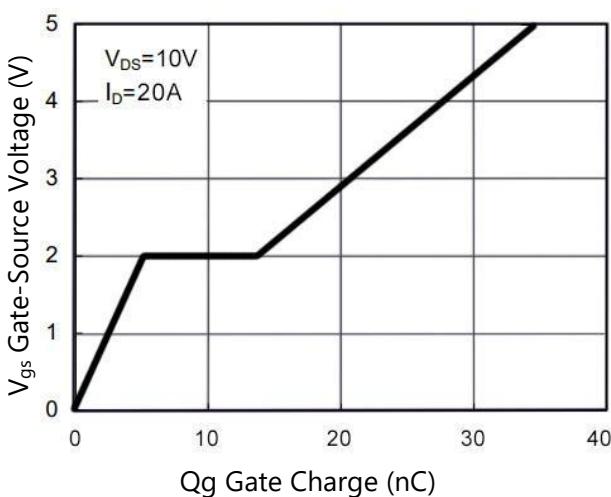
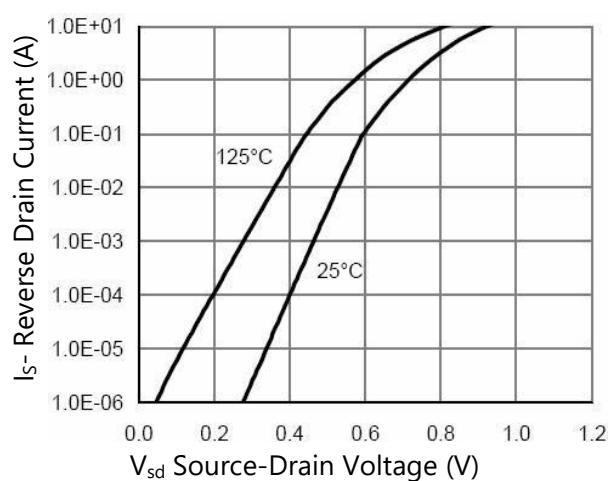
Diode Forward Voltage ^(Note2)	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=1\text{A}$	-	-	1.2	V
Diode Forward Current ^(Note1)	I_{S}		-	-	20	A

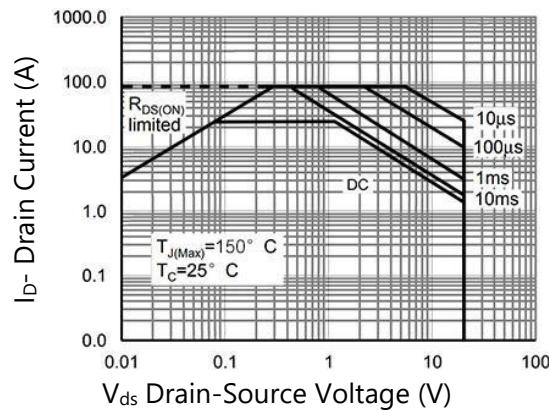
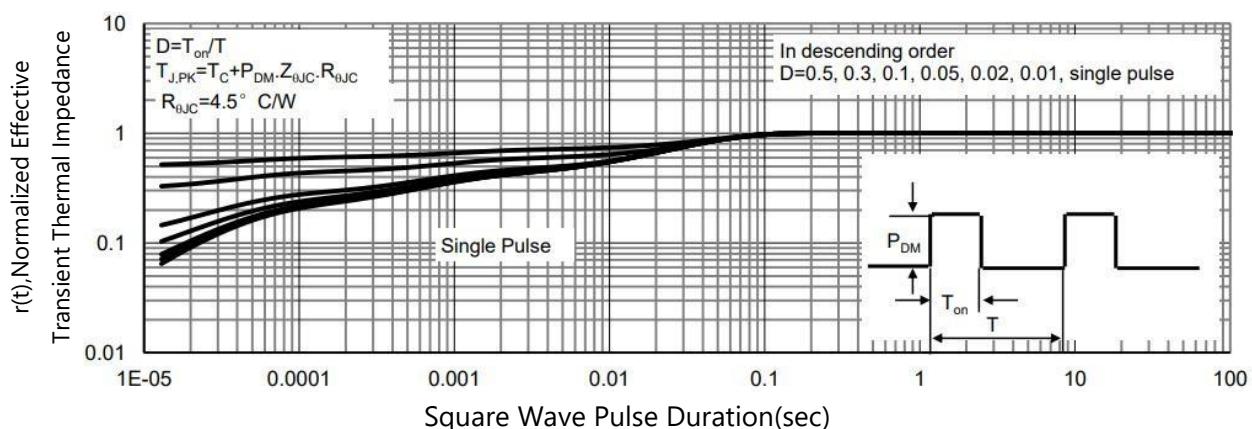
Note 1. Surface Mounted on FR4 Board, $t \leq 10$ sec.

Note 2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

Note 3. Guaranteed by design, not subject to product.

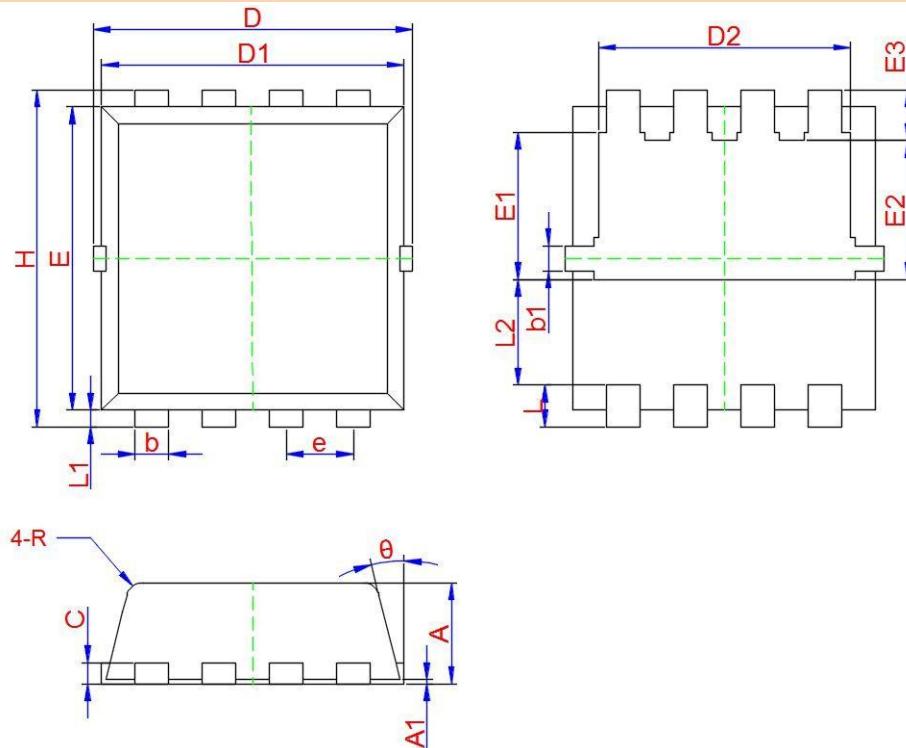

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 1. Switching Test Circuit

Figure 2. Switching Waveform

Figure 3. Power Dissipation

Figure 4. Drain Current

Figure 5. Output Characteristics

Figure 6. R_{dson} vs Drain Current



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 7. Transfer Characteristics

Figure 8. R_{dson} vs Case Temperature

Figure 9. R_{dson} vs V_{gs}

Figure 10. Capacitance vs V_{DS}

Figure 11. Gate Charge

Figure 12. Source- Drain Diode Forward



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS
Figure 13. Safe Operation Area

Figure 14. Normalized Maximum Transient Thermal Impedance


PACKAGE INFORMATION

PDFN3.3x3.3-8L



Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.700	0.800	0.900
A1	0.000	0.030	0.050
b	0.240	0.300	0.350
b1	0.080	0.130	0.180
c	0.152 TYP.		
D	3.250	3.320	3.400
D1	3.050	3.150	3.250
D2	2.400	2.500	2.600
E	3.000	3.100	3.200
E1	1.350	1.450	1.550
E2	1.200	1.300	1.400
E3	0.400	0.500	0.600
e	0.650 TYP.		
H	3.200	3.300	3.400
L	0.300	0.400	0.500
L1	0.100	0.150	0.200
L2	1.130 TYP.		
R	0.200 TYP.		
θ	6°	10°	14°